



Material Content Data Sheet



Sales Product Name		IPD30N08S2L-21		Issued		1. August 2018		
MA#		MA000260978						
Package		PG-TO252-3-11		Weight*		371.48 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	4.029	1.08	1.08	10845	10845
leadframe	inorganic material	phosphorus	7723-14-0	0.065	0.02		174	
	non noble metal	iron	7439-89-6	0.215	0.06		580	
	non noble metal	copper	7440-50-8	215.017	57.87	57.95	578818	579572
	non noble metal	aluminium	7429-90-5	0.921	0.25	0.25	2478	2478
wire	non noble metal	aluminium	7429-90-5	0.921	0.25	0.25	2478	2478
encapsulation	organic material	carbon black	1333-86-4	1.250	0.34		3364	
	plastics	epoxy resin	-	21.869	5.89		58871	
	inorganic material	silicondioxide	60676-86-0	101.847	27.42	33.65	274169	336404
leadfinish	non noble metal	tin	7440-31-5	3.740	1.01	1.01	10068	10068
plating	inorganic material	phosphorus	7723-14-0	0.000	0.00		1	
	non noble metal	nickel	7440-02-0	0.091	0.02	0.02	244	245
solder	non noble metal	tin	7440-31-5	0.065	0.02		174	
	noble metal	silver	7440-22-4	0.081	0.02		217	
	non noble metal	lead	7439-92-1	3.085	0.83	0.87	8304	8695
heatspreader	inorganic material	phosphorus	7723-14-0	0.006	0.00		16	
	non noble metal	iron	7439-89-6	0.019	0.01		52	
	non noble metal	copper	7440-50-8	19.177	5.16	5.17	51625	51693
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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